



## The Commissioner of Patents and Trademarks Washington, D.C. 20231

Tansmitted brewith for filing is the the patent application of:  Warren M. Farnworth, Alan G. Wood, Trung T. Doan, David R. Hembree	•
For: BONDPAD ATTACHMENTS HAVING SELF-LIMITING PROPERTIES FOR PENETRATION OF	
Prior Application: SEMICONDUCTOR DIE. (as amended)	
Examiner: unassigned Art Unit: unassigned	
This is a Request for Filing a:	
☐ Divisional	
application under 37 CFR 1.60, of pending prior application serial no. 0_8/_ 073,003 filed on (date) 6/7/93 of (inventors) Warren M. Farnworth et al. for (invention title) BONDPAD ATTACHMENTS USED TO TEMPORARILY CONNECT SEMICONDUCTOR DI	Ε.
Enclosed are:	
Original specification ( pages including Abstract)	
☐ Executed Declaration	
sheets of drawings	
An assignment of the invention to	
☐ Information Disclosure Statement including copies	
1) Copy of Prior Application as Filed Which is Attached:	
I hereby verify that the attached papers are a true copy of what is shown in my records to be the above identified prior application, including the oath or declaration originally filed (37 CFR 1.60)	
The copy of the papers of prior application as filed which are attached are as follows:	
X 25 page(s) of specifications	
X 25 page(s) of claims	
X 1 page(s) of abstract	
2 9 page(s) of drawings	
(also complete part 4 below if drawings are to be transferred)	
in accordance with the indication required by 37 CFR 60(b) my records reflect that the original signed declaration showing applicant's signature was filed on	
2) Amendments:	
Cancel in this application original claims of the prior application before calculating the filing fee. (At least one original independent claim must be retained for filing purposes.)	
X A preliminary amendment is enclosed.	

Amend the specifications by inserting before the first line the sente "This is a	11
<ul> <li>□ continuation</li></ul>	
International Application filed on and which designated the U.S."	
and which designated the U.S."	
·	
4) Drawings:	
Do not check the following box if prior case is not to be abandoned.	
Transfer the drawings from the prior application to this application below, abandon said prior application as of the the filing date acco A duplicate copy of this request is enclosed for filing in the prior a only be used if signed by (1) applicant, (2) assignee of record or (1) record authorized by 37 CFR 1.138 and before payment of issue from the prior application of the prior application of the prior application as of the the filing date account application as of the prior application as of the p	ded this application.  plication file. (May ) attorney or agent of
☐ Transfer the following sheet(s) of drawings from the prior applica	on to this application.
New drawings are enclosed	
5) Assignment:	
The prior application is assigned of record to:	
APPLICANT: Micron Technology, Inc.	
ADDRESS: 2805 E. Columbia Road	
Boise, Idaho 83706	
Assignment recorded in PTO on <u>June 7, 199</u> Reel <u>6582</u> Frame <u>044</u>	
6) Fee Calculation:	
The filing fee has been calculated as shown below:	
(0-1-1) (0-1-2)*	
(Col. 1) (Col. 2)*  For: No. Filed No. Extra Rate	Fee
Basic Fee:	\$ 710
Total Claims: 27 - 20 = * 7 x 22 =	<del></del>
Indep Claims: $4 - 3 =                                 $	
☐ Multiple Dependent Claims Presented + 230 =	
* If the difference in Col. 1 is less than zero, enter '0' in Col. 2	l: \$ <sub>938</sub>

Assignment Recording Fee, if applicable

\$ <u>40</u>

Case I	et No.	91-62.7

7) Payment of Fees:			
Please charge my Deposit Account No. 13-3 A duplicate copy of this sheet is enclosed.	092 in the amount of \$ 938		
A check in the amount of \$ recording fee (if applicable) is enclosed.	_ to cover the filing fee and assignment		
The Commissioner is hereby authorized to che with this communication or credit any overpart A duplicate copy of this sheet is enclosed.	narge payment of the following fees associated ayment to Deposit Account No. 13-3092.		
<ul><li>Any additional filing fees required und</li><li>Any patent application processing fees</li></ul>			
The Commissioner is hereby authorized to che pendency of this application or credit any over A duplicate copy of this sheet is enclosed.	targe payment of the following fees during the erpayment to Deposit Account No. 13-3092.		
Any patent application processing fees	under 37 CFR 1.17.		
pursuant to 37 CFR 1.311(b).	before mailing of the Notice of Allowance,		
Any filing fees under 37 CFR 1.16 for	presentation of extra claims.		
8) Maintenance of Copendency of Prior Ap	plication:		
Applicant petitions to extend the term in the p is filed. Please charge any fees to deposit ac A triplicate copy of this sheet is enclosed.	ending prior application until this application count No. 13-3092.		
9) Abandonment of Prior Application (if a	pplicable):		
Please abandon the prior application at a time the petition for extension of time or to revive to make this application copending with said	in that application is granted a filing date so as		
I hereby declare further that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code, and that such willful false statements may jeopardize the validity of the application or any patent issuing thereon.			
I hereby certify that this paper and the documents referred to as enclosed therein are being deposited with the United States Postal Service on this date 9/13/93 in an envelope as "Express Mail Post Office to Addressee"  Mailing Label Number RB803890049 (Signature of person mailing papers)	Stanley N. Protigal Attorney of Record Reg. No. 28,657 Micron Semiconductor, Inc. 2805 East Columbia Rd. Boise, ID 83706		

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